

T-1 (3mm) TRI-LEVEL LED INDICATOR

Part Number: L-934SA/1I1Y1GD

High Efficiency Red

Yellow Green

Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

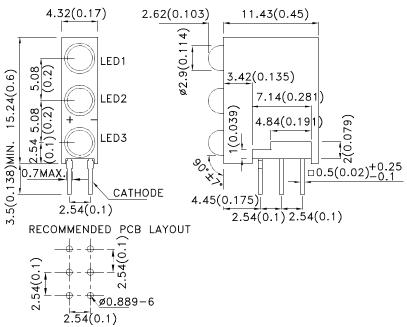
The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions

LED1:RED LED2:YELLOW LED3:GREEN



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAB1226 **REV NO: V.7A DATE: NOV/29/2013** PAGE: 1 OF 7 APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.M.Chen ERP: 1102013280





Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-934SA/1I1Y1GD	High Efficiency Red (GaAsP/GaP)	Dod Diffused	12	30	40°
		Red Diffused	*10	*20	
	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	- 40° - 40°
		reliow Diliused	*8	*15	
	Green (GaP)	Green Diffused	10	25	
		Green Dinused	*10	*25	

- Notes:
 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Yellow Green	627 590 565		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Yellow Green	617 588 568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Yellow Green	45 35 30		nm	IF=20mA
С	Capacitance	High Efficiency Red Yellow Green	15 20 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Yellow Green	2.1 2.2 2.2	2.5 2.5 2.5	V	IF=20mA
ĪR	Reverse Current	High Efficiency Red Yellow Green		10 10 10	uA	VR=5V

- 1.Wavelength: +/-1nm.
 2. Forward Voltage: +/-0.1V.
 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

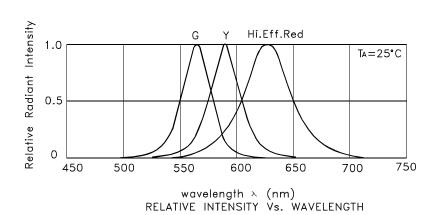
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Yellow	Green	Units		
Power dissipation	75	62.5	62.5	mW		
DC Forward Current	30	25	25	mA		
Peak Forward Current [1]	160	140	140	mA		
Reverse Voltage	5 V					
Operating/Storage Temperature	-40°C To +85°C					
Lead Solder Temperature [2]	260°C For 3 Seconds					
Lead Solder Temperature [3]	260°C For 5 Seconds					

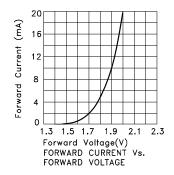
Notes:

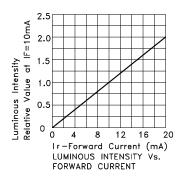
- 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
 5mm below package base.

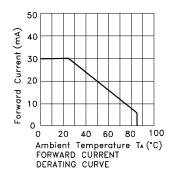
DATE: NOV/29/2013 SPEC NO: DSAB1226 **REV NO: V.7A** PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1102013280 DRAWN: Q.M.Chen

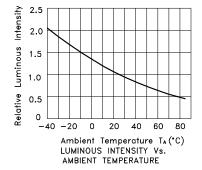


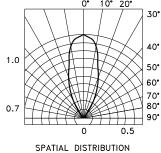
L-934SA/1I1Y1GD High Efficiency Red







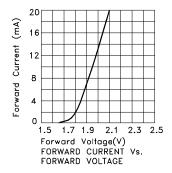


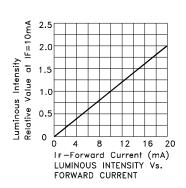


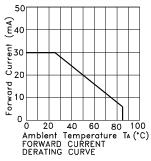
SPEC NO: DSAB1226 REV NO: V.7A DATE: NOV/29/2013 PAGE: 3 OF 7

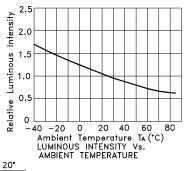
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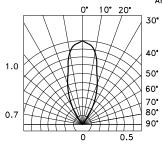
Yellow









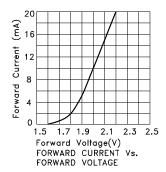


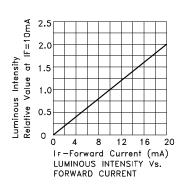
SPATIAL DISTRIBUTION

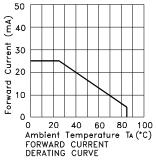
SPEC NO: DSAB1226 REV NO: V.7A DATE: NOV/29/2013 PAGE: 4 OF 7

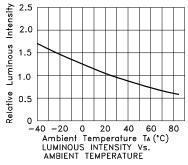
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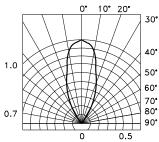
Green







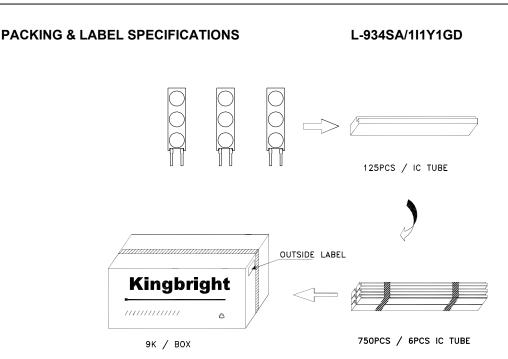




SPATIAL DISTRIBUTION

SPEC NO: DSAB1226 REV NO: V.7A DATE: NOV/29/2013 PAGE: 5 OF 7

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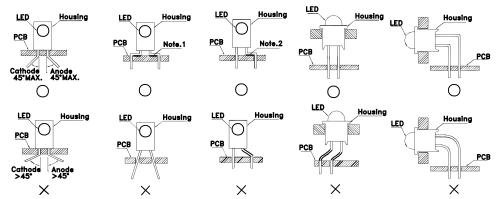
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 SPEC NO: DSAB1226
 REV NO: V.7A
 DATE: NOV/29/2013
 PAGE: 6 OF 7

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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

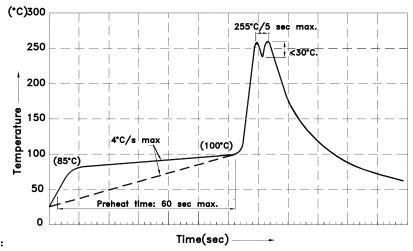


" \bigcirc " Correct mounting method " \times " Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

SPEC NO: DSAB1226 REV NO: V.7A DATE: NOV/29/2013 PAGE: 7 OF 7

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